

This issue marks an anniversary of the JOURNAL OF ELECTRONIC PACKAGING. The first issue appeared in March 1989 in response to the crucial need for a source of useful information in this important field of modern engineering. The Journal was also intended to serve as a forum for all those using Engineering Mechanics and Thermal Analysis in Electronic Packaging. By all considerations, it has been a successful year. The number of our subscribers and contributors has grown tremendously. The success of the Journal should be attributed, first of all, to its unique charter to address problems in which electronic packages are treated as structures, and/or in which quantitative, rather than qualitative, analyses are necessary. The insight of the mechanical engineer in such problems is indispensable. Of course, the success of the Journal is due also to its great variety, high technical level, yet practicality.

With this in mind, the present issue is not very different from the previous ones. What makes it different, however, is that it chiefly contains papers presented at the *First ASME Symposium on Structural Analysis in Microelectronics*. The conference was organized jointly by the Electrical and Electronic Packaging Division and the Elasticity Committee of the Applied Mechanics Division of The Society of Mechanical Engineers. It was held at the 1989 ASME Winter Annual Meeting, December 10-15, in San Francisco, California. Engineers and scientists applying or interested in applying mechanical approaches in microelectronics, were brought together to bridge the gap between the state-of-the-art applied science and the everyday needs of the packaging technology. Specific sessions were on packaging, modeling, thermal stress, and multimaterial structures. The sessions were chaired by W. T. Chen, P. A. Engel, E. Suhir, F. Erdogan, K. S. Kim, L. M. Keer, R. Hetnarski, and I. M. Daniel.

The success of the conference exceeded all expectations, and the unanimous recommendation of the participants was that such symposia be held annually, during ASME winter meetings. We invite you to present the results of your recent



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work to the 1990 Symposium. You will find a Call for Papers in this issue. Outstanding papers presented at the upcoming and the future symposia will be published in the Journal.

Looking forward to seeing you in Dallas at the ASME Winter Annual Meeting.

*Ephraim Suhir*

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**Senior Associate Editor**